RELIABILITY REPORT

FOR

MAX6326URxx

PLASTIC ENCAPSULATED DEVICES

November 28, 2002

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Written by

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Conclusion

The MAX6326 successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

Table of Contents

I. Device Description

A. General

The MAX6326 microprocessor (µP) supervisory circuit monitors the power supplies in µP and digital systems. This devices provides excellent circuit reliability and low cost by eliminating external components and adjustments when used with 2.5V, 3V, 3.3V, and 5V powered circuits.

This circuits performs a single function: it asserts a reset signal whenever the V_{CC} supply voltage declines below a preset threshold, keeping it asserted for at least 100ms after V_{CC} has risen above the reset threshold. The MAX6326 (push-pull) has an active-low reset output. The part is guaranteed to be in the correct state for V_{CC} down to 1V. The reset comparator is designed to ignore fast transients on V_{CC}. Reset thresholds are factory-trimmable between 2.2V and 4.63V, in approximately 100mV increments. Twenty-one standard versions are available. Contact the factory for availability of nonstandard versions.

Ultra-low supply currents makes this part ideal for use in portable equipment. The device is available in space-saving SOT23 and SC70 packages.

B. Absolute Maximum Ratings

Item	Rating
Terminal Voltage (with respect to GND)	
VCC	-0.3V to +6V
RESET, RESET (push-pull)	-0.3V to (VCC + 0.3V)
Input Current (VCC)	20mA
Output Current (RESET, RESET)	20mA
Rate of Rise (VCC)	100V/µs
Operating Temperature Range	-40°C to +85°C
Storage Temperature Range	-65°C to +150°C
Lead Temperature (soldering, 10s)	+300°C
Continuous Power Dissipation (TA = +70°C)	
3-Pin SOT23	320mW
Derates above +70°C	
3-Pin SOT23	4.0mW/°C

II. Manufacturing Information

A. Description:	3-Pin Ultra Low Power uP Reset Circuits
B. Process:	S12 (Standard 1.2 micron silicon gate CMOS)
C. Number of Device Transistors:	419
D. Fabrication Location:	Oregon or California, USA
E. Assembly Location:	Malaysia
F. Date of Initial Production:	October, 1997

III. Packaging Information

A. Package Type:	**3-Lead SOT23**
B. Lead Frame:	Alloy 42
C. Lead Finish:	Solder Plate
D. Die Attach:	Non-Conductive Epoxy
E. Bondwire:	Gold (1.0 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	# 05-1601-0043
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard JESD22-A112:	Level 1

IV. Die Information

A. Dimensions:	44 x 31 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Aluminum/Si (Si = 1%)
D. Backside Metallization:	None
E. Minimum Metal Width:	1.2 microns (as drawn)
F. Minimum Metal Spacing:	1.2 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts: Jim Pedicord (Reliability Lab Manager)
Bryan Preeshl (Executive Director of QA)
Kenneth Huening (Vice President)

B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects.

C. Observed Outgoing Defect Rate: < 50 ppm

D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in **Table 1**. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{192 \times 4389 \times 178 \times 2}$$

(Chi square value for MTTF upper limit)

Temperature Acceleration factor assuming an activation energy of 0.8eV

$\lambda = 6.10 \times 10^{-9}$ $\lambda = 6.10$ F.I.T. (60% confidence level @ 25°C)

This low failure rate represents data collected from Maxim's reliability qualification and monitor programs. Maxim also performs weekly Burn-In on samples from production to assure reliability of its processes. The reliability required for lots which receive a burn-in qualification is 59 F.I.T. at a 60% confidence level, which equates to 3 failures in an 80 piece sample. Maxim performs failure analysis on rejects from lots exceeding this level. The attached Burn-In Schematic (Spec. # 06-4392) shows the static circuit used for this test. Maxim also performs 1000 hour life test monitors quarterly for each process. This data is published in the Product Reliability Report (**RR-1M**).

B. Moisture Resistance Tests

Maxim evaluates pressure pot stress from every assembly process during qualification of each new design. Pressure Pot testing must pass a 20% LTPD for acceptance. Additionally, industry standard 85°C/85%RH or HAST tests are performed quarterly per device/package family.

C. E.S.D. and Latch-Up Testing

The MS17 die type has been found to have all pins able to withstand a transient pulse of ±2000V, per Mil-Std-883 Method 3015 (reference attached ESD Test Circuit). Latch-Up testing has shown that this device withstands a current of ±200mA.

Table 1
Reliability Evaluation Test Results

MAX6326URxx

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	PACKAGE	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)					
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality		178	0
Moisture Testing (Note 2)					
Pressure Pot	Ta = 121°C P = 15 psi. RH= 100% Time = 168hrs.	DC Parameters & functionality	SOT23	77	0
85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality		77	0
Mechanical Stress (Note 2)					
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters		77	0

Note 1: Life Test may represent DIP qualification packages.
Note 2: Generic Package/Process data

Attachment #1

TABLE II. Pin combination to be tested. 1/ 2/

	Terminal A (Each pin individually connected to terminal A with the other floating)	Terminal B (The common combination of all like-named pins connected to terminal B)
1.	All pins except V_{PS1} 3/	All V_{PS1} pins
2.	All input and output pins	All other input-output pins

1/ Table II is restated in narrative form in 3.4 below.
2/ No connects are not to be tested.
3/ Repeat pin combination I for each named Power supply and for ground

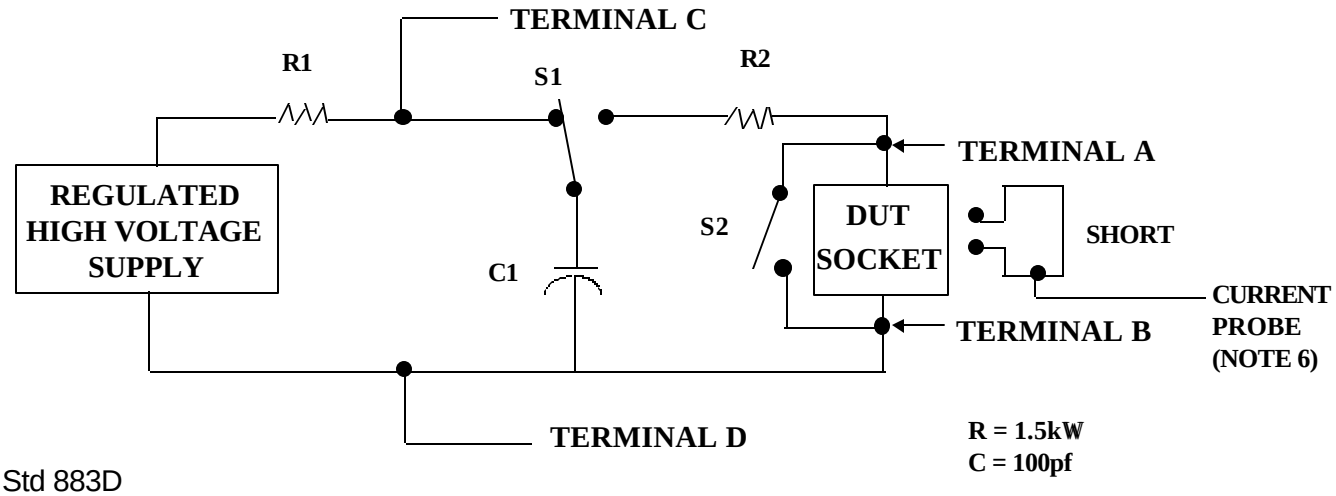
(e.g., where V_{PS1} is V_{DD}, V_{CC}, V_{SS}, V_{BB}, GND, $+V_S$, $-V_S$, V_{REF}, etc).

3.4 Pin combinations to be tested.

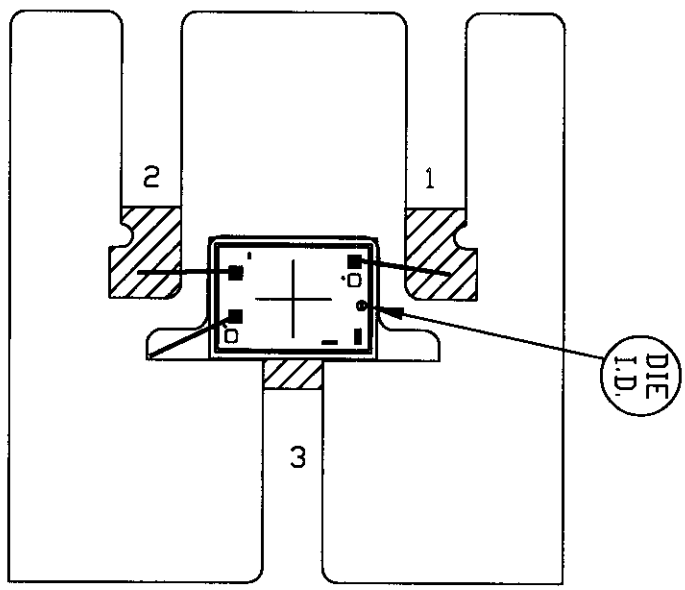
a. Each pin individually connected to terminal A with respect to the device ground pin(s) connected to terminal B. All pins except the one being tested and the ground pin(s) shall be open.

b. Each pin individually connected to terminal A with respect to each different set of a combination of all named power supply pins (e.g., V_{SS1}, or V_{SS2} or V_{SS3} or V_{CC1}, or V_{CC2}) connected to terminal B. All pins except the one being tested and the power supply pin or set of pins shall be open.

c. Each input and each output individually connected to terminal A with respect to a combination of all the other input and output pins connected to terminal B. All pins except the input or output pin being tested and the combination of all the other input and output pins shall be open.



Mil Std 883D
Method 3015.7
Notice 8

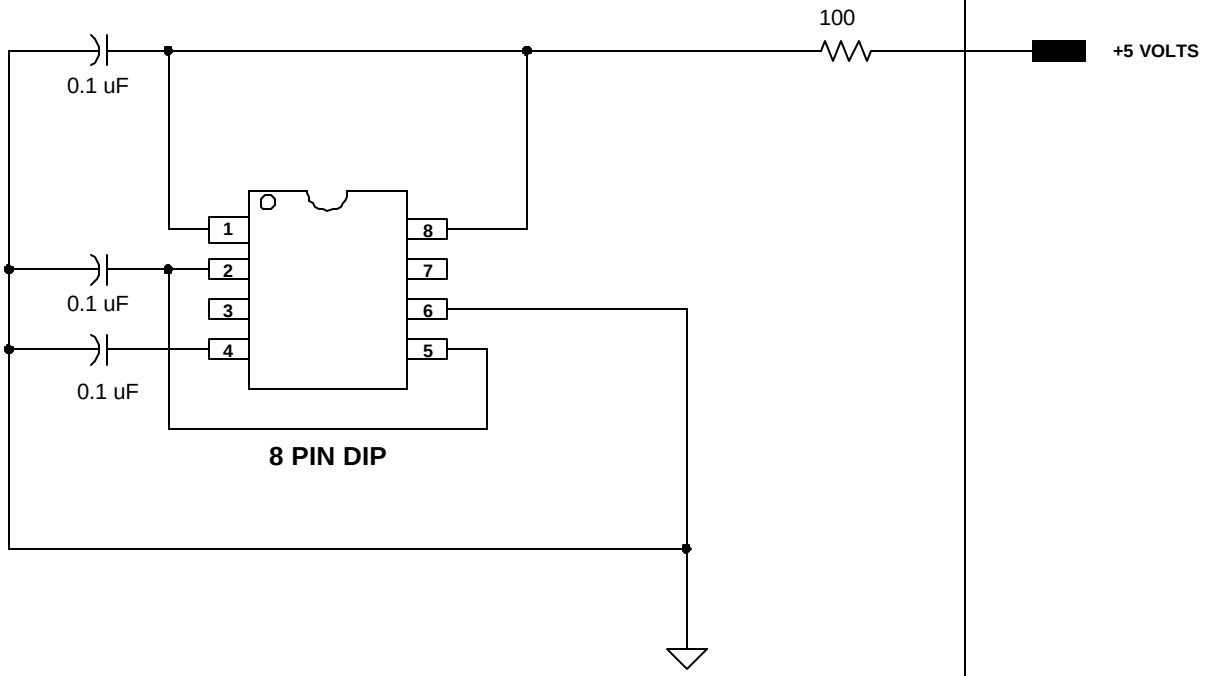


USE NON-CONDUCTIVE EPOXY

PKG. CODE: U3-1		SIGNATURES	DATE	MAXIM CONFIDENTIAL & PROPRIETARY	
CAV./PAD SIZE: 45X32	PKG. DESIGN			BOND DIAGRAM #: 05-1601-0043	REV: B

ONCE PER SOCKET

ONCE PER BOARD



8 PIN DIP

DEVICES: MAX 6326/6327/6328/6346/6347/6348/6375/6376/6377/6378/6379/6380/750/750A/758/758A
MAX. EXPECTED CURRENT = 2 mA

NOTES: MS45 only for MAX 6326-6380.